

**PATENT APPLICATION TRANSMITTAL LETTER**  
(Large Entity)

Docket No.  
65.0338DIV

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith for filing under 35 U.S.C. 111 and 37 C.F.R. 1.53 is the patent application of:

Chun-Cheng Tsao and John Valliant

For: **METHOD AND APPARATUS FOR GLOBAL DIE THINNING AND POLISHING OF FLIP-CHIP PACKAGED INTEGRATED CIRCUITS**

Enclosed are:

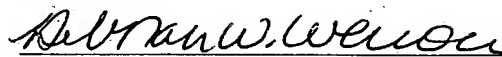
- ☒ Certificate of Mailing with Express Mail Mailing Label No. ER 496109970 US  
☒ Six (6) sheets of drawings.  
☐ A certified copy of a application.  
☒ Declaration ☒ Signed. ☐ Unsigned.  
☒ Power of Attorney  
☐ Information Disclosure Statement  
☐ Preliminary Amendment  
☒ Other: Copy of orig. Declaration; copy of letter from Petitions Office granting 1.47(a) status; cover letter

**CLAIMS AS FILED**

For	#Filed	#Allowed	#Extra	Rate	Fee
Total Claims	29	- 20 =	9	x \$18.00	\$162.00
Indep. Claims	5	- 3 =	2	x \$86.00	\$172.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
BASIC FEE					\$770.00
TOTAL FILING FEE					\$1,104.00

- ☐ A check in the amount of to cover the filing fee is enclosed.  
☒ The Director is hereby authorized to charge and credit Deposit Account No. 19-0603 as described below.  
☒ Charge the amount of \$1,104.00 as filing fee.  
☒ Credit any overpayment.  
☒ Charge any additional filing fees required under 37 C.F.R. 1.16 and 1.17.  
☐ Charge the issue fee set in 37 C.F.R. 1.18 at the mailing of the Notice of Allowance, pursuant to 37 C.F.R. 1.311(b).

Dated: Oct. 23, 2003

  
Signature

Deborah Wenocur, Reg. No. 40,221  
Agent for Applicant  
Legal Department, NPTest, LLC  
c/o Lasagne Edwards  
150 Baytech Drive  
San Jose, CA 95134-2302

CC:

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Applicant:	Chung-Chen Tsao and John Valliant	) Grp Art Unit: n/a
		)
Assignee:	NPTesT, LLC	) Ex: n/a
		)
Serial Number:	unknown	)
		)
Filed:	n/a	)
		)
For:	METHOD AND APPARATUS FOR	)
	GLOBAL DIE THINNING AND	)
	POLISHING OF FLIP-CHIP	)
	PACKAGED INTEGRATED	)
	CIRCUITS	)
		)

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

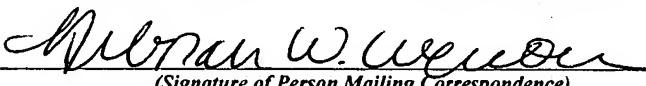
Dear Sir,

The enclosed divisional patent application is being submitted with a new Declaration/POA, signed by the first-named inventor only, so as to explicitly claim priority to the parent application, as well as to name a new agent of record. Also enclosed is a copy of the prior Declaration from the parent application, along with a copy of the letter from the Office of Petitions according to the parent application status under 37 CFR 1.47(a), regarding non-signing inventor John Valliant who could not be located after diligent effort.

Respectfully submitted,

Robert W. Wilson

Deborah W. Wenocur  
Reg. No. 40,221  
Agent for Applicant  
Tel. (650) 493-3849

<b>CERTIFICATE OF MAILING BY "EXPRESS MAIL" (37 CFR 1.10)</b> Applicant(s): Chun-Cheng Tsao and John Valliant			Docket No. 65.0338DIV
Serial No. n/a	Filing Date n/a	Examiner n/a	Group Art Unit n/a
Invention: <b>METHOD AND APPARATUS FOR GLOBAL DIE THINNING AND POLISHING OF FLIP-CHIP PACKAGED INTEGRATED CIRCUITS</b>			
<p>I hereby certify that the following correspondence:</p> <div style="border: 1px solid black; height: 50px; margin: 10px 0;"></div> <p style="text-align: center;"><i>(Identify type of correspondence)</i></p> <p>is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on</p> <p style="text-align: center;"><u>October 24, 2003</u> <i>(Date)</i></p> <div style="text-align: right; margin-top: 20px;"><p><u>Deborah W. Wenocur</u> <i>(Typed or Printed Name of Person Mailing Correspondence)</i></p><p> <i>(Signature of Person Mailing Correspondence)</i></p><p><u>ER 496109970 US</u> <i>("Express Mail" Mailing Label Number)</i></p></div>			
<p><b>Note: Each paper must have its own certificate of mailing.</b></p>			